

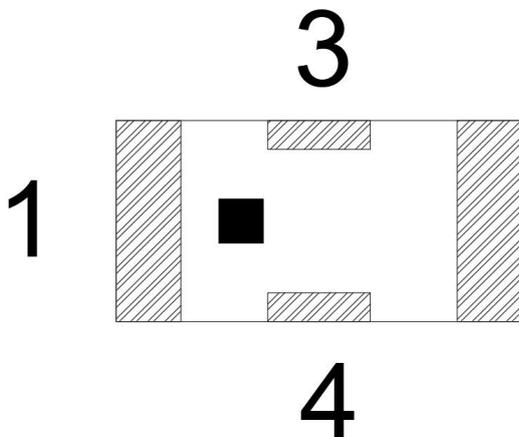
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

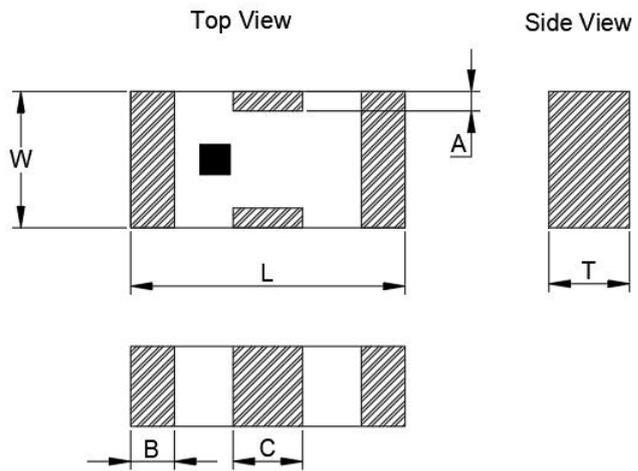
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	6000~6600		3.5
2	Ripple	6000~6600	±0.6	
3	VSWR	6000~6600		1.5
4	Attenuation (dBc)	6900~7400	15	
5	In/Output Impedance (Ω)		50	

Construction

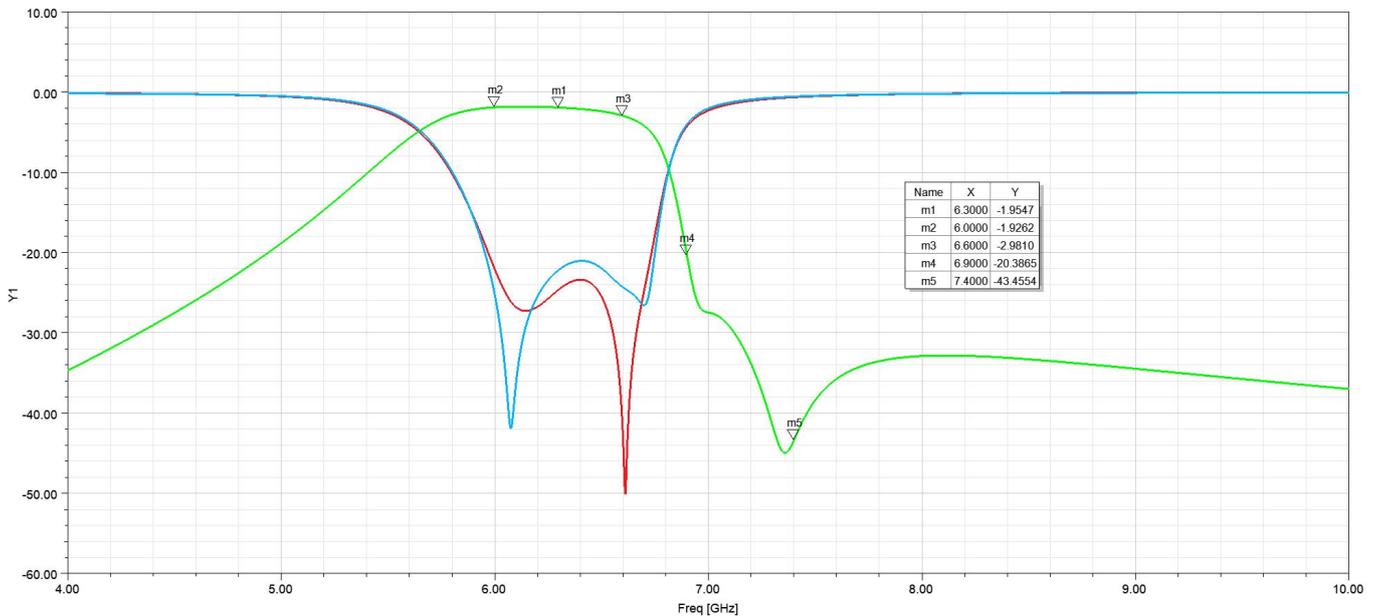


PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

Dimensions

Figure	Symbol	Dimension (mm)
	L	3.20±0.20
	W	1.60±0.20
	T	0.94±0.10
	A	0.23±0.10
	B	0.51±0.10
	C	0.81±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.